

Rev.A Se .-2022

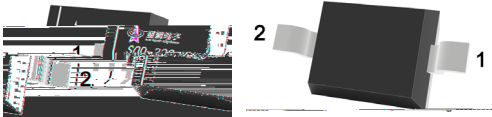
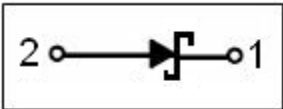
SOD-323

Sc k Di e i a SOD-323 Pla ic Packa e.

AEC-Q101

L w iive re re r ,Q alifie AEC-Q101 Sa ar f rHi Reliabili ,HF Pr c .

Ge eral r e,Mee e ri e re ire e f a ive a lica i .

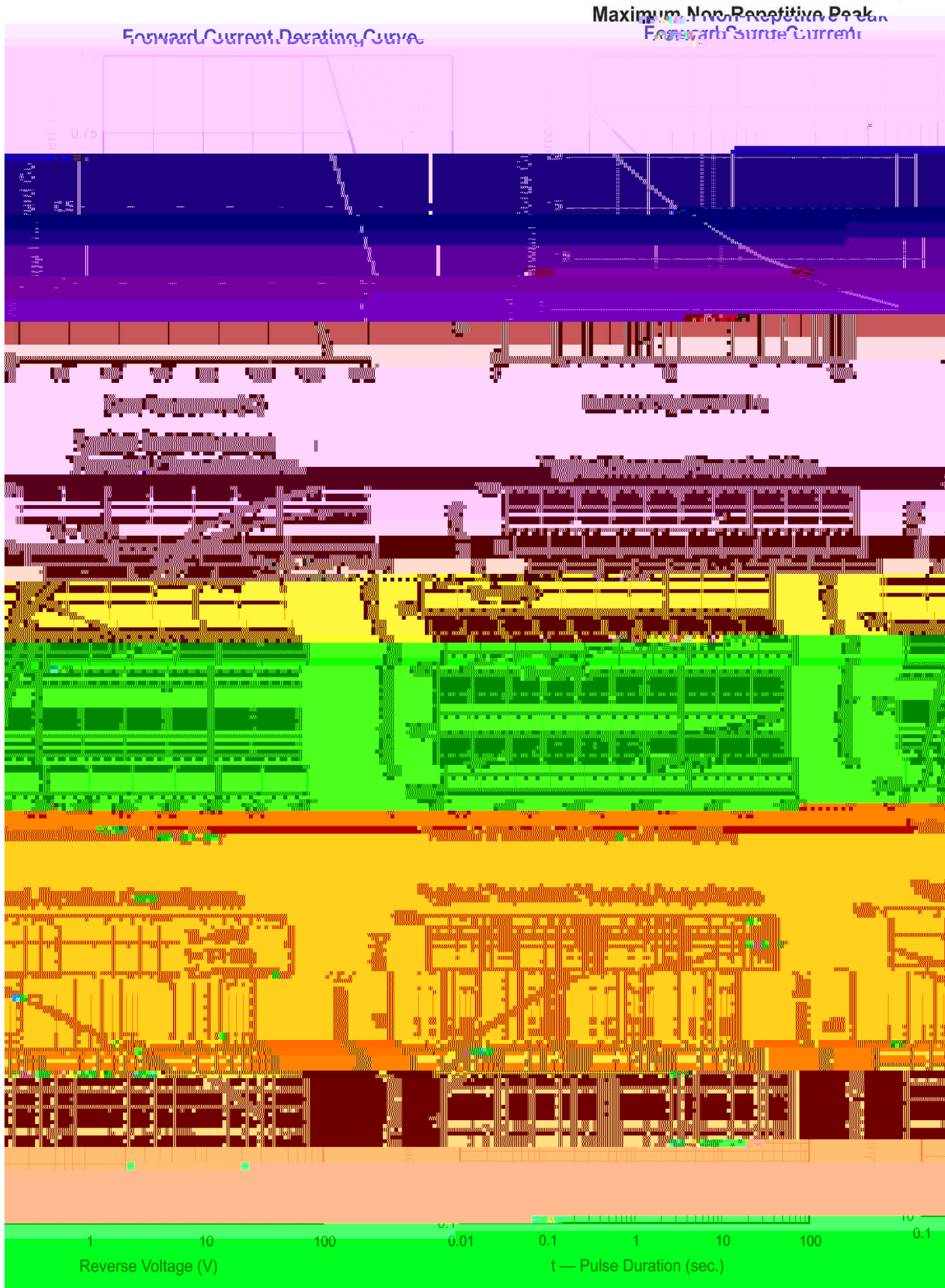


PIN1:Ca e PIN2:A e

M el	BRB5817WSQ	BRB5818WSQ	BRB5819WSQ
Marki	QSJ	QSK	QSL

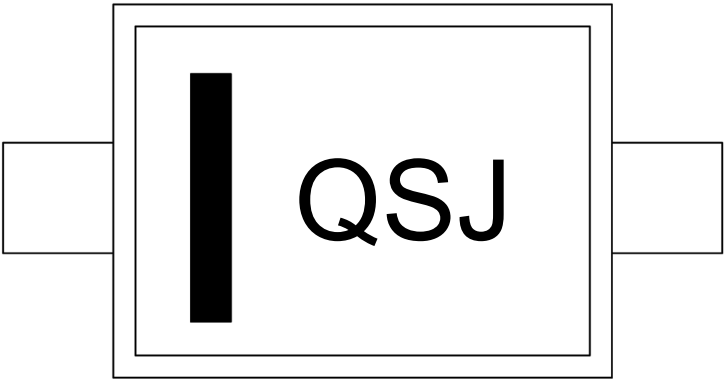
Parameter	Symbol	Rating			Unit
		BRB5817WSQ	BRB5818WSQ	BRB5819WSQ	
Peak Reverse Voltage, Working Peak Reverse Voltage, DC Reverse Voltage	V_{RRM} V_{RWM} V_R	20	30	40	V
RMS Reverse Voltage	V_{RMS}	14	21	28	V
Average Rectified Forward Current	I_F	1			A
Non-Reverse Peak Forward Surge Current	I_{FSM}	25			A
Power Dissipation	P	200			W
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	500			/W
Junction Storage Temperature Range	T_J, T	-65 ~ 125			

Parameter	Symbol	Temperature		Rating		Unit
				MIN	MAX	
Reverse Breakdown Voltage	$V_{(BR)}$	$I_R=1A$	BRB5817WSQ	20		V
			BRB5818WSQ	30		
			BRB5819WSQ	40		
Peak Forward Voltage	V_{FM}	$I_F=0.1A$	BRB5817WSQ		0.32	V
			BRB5818WSQ		0.35	
			BRB5819WSQ		0.4	
		$I_F=1A$	BRB5817WSQ		0.45	
			BRB5818WSQ		0.55	
			BRB5819WSQ		0.60	
		$I_F=3A$ ($<5^\circ$)	BRB5817WSQ		0.75	
			BRB5818WSQ		0.875	
			BRB5819WSQ		0.90	
Maximum Reverse Current	I_{RM}	$V_R=V_{RWM}$		1		A
Junction Capacitance	C_J	$V_R=4V$ $f=1.0MHz$		120		F



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Q

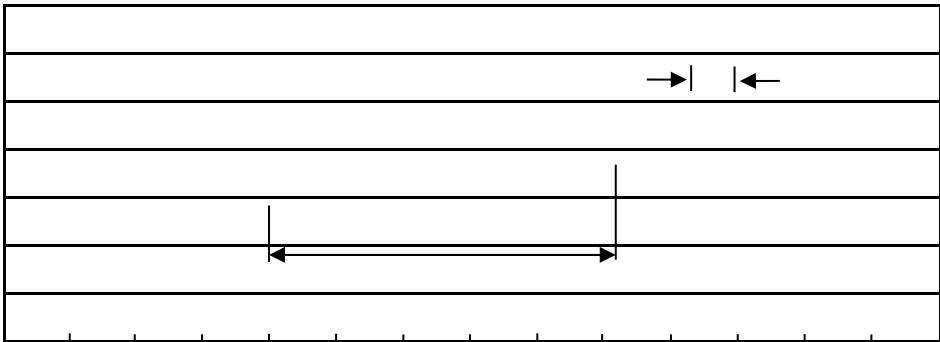
SJ

N e:

Q: A bile al e -free r c C e

SJ: Pr c T e

Temperature Profile for IR Reflow Soldering(Pb-Free)



N e:

- 1

150 200

60 120 ec;

1.Pre ea i :150 200 ,Ti e:60 120 ec.
- 2

255±5

5±0.5 ec;

2.Peak Te .:255±5 ,D ra i :5±0.5 ec.
- 3

2 10 / ec.

3.C li S ee :2 10 / ec.

260±5

10±1 ec.

Te .:260±5

Ti e:10±1 ec

/ REEL

Packa e T e	U i					Di e i (i ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOD-323	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205